

1. Global joint venture starts operations as WeEn Semiconductors

Dear customer,

As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

In this document where the previous NXP references remain, please use the new links as shown below.

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If you have any questions related to this document, please contact our nearest sales office via email or phone (details via <u>salesaddresses@ween-semi.com</u>).

Thank you for your cooperation and understanding,

WeEn Semiconductors



DISCRETE SEMICONDUCTORS



Product specification

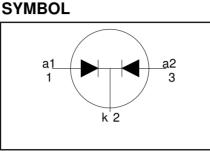
July 1998



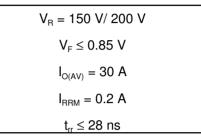
BYV42E, BYV42EB series

FEATURES

- · Low forward volt drop
- · Fast switching
- · Soft recovery characteristic
- Reverse surge capability
 High thermal cycling performance
- · Low thermal resistance



QUICK REFERENCE DATA



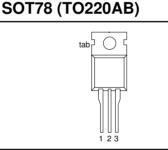
GENERAL DESCRIPTION

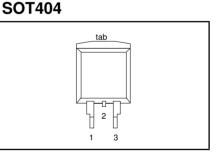
Dual, ultra-fast, epitaxial rectifier diodes intended for use as output rectifiers in high frequency switched mode power supplies.

The BYV42E series is supplied in the SOT78 conventional leaded package. The BYV42EB series is supplied in the SOT404 surface mounting package.

PINNING

PIN DESCRIPTION anode 1 (a) 1 cathode (k) 1 2 3 anode 2 (a) cathode (k) tab





LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER CONDITIONS MIN. MAX.		AX.	UNIT		
V _{RRM} V _{RWM} V _R	Peak repetitive reverse voltage Crest working reverse voltage Continuous reverse voltage	BYV42E / BYV42EB $T_{mb} \le 144^{\circ}C$		-150 150 150 150	-200 200 200 200	V V V
I _{O(AV)}	Average rectified output current (both diodes conducting)	square wave $\delta = 0.5$; T _{mb} ≤ 108 °C	-	30		A
I _{FRM}	Repetitive peak forward current per diode	t = 25 μ s; δ = 0.5; T _{mb} ≤ 108 °C	-	3	0	A
I _{FSM}	Non-repetitive peak forward current per diode	t = 10 ms t = 8.3 ms sinusoidal; with reapplied	-		50 50	A A
I _{RRM}	Repetitive peak reverse current		-	0	.2	A
I _{RSM}	Non-repetitive peak reverse current per diode	t _p = 100 μs	-	0	.2	A
T _{stg} T _i	Storage temperature Operating junction temperature		-40 -		50 50	Ĵ Ĵ

 It is not possible to make connection to pin 2 of the SOT404 package
 SOT78 package, For output currents in excess of 20 A, the cathode connection should be made to the mounting tab.

BYV42E, BYV42EB series

ESD LIMITING VALUE

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Vc	Electrostatic discharge capacitor voltage	Human body model; C = 250 pF; R = 1.5 kΩ	-	8	kV

THERMAL RESISTANCES

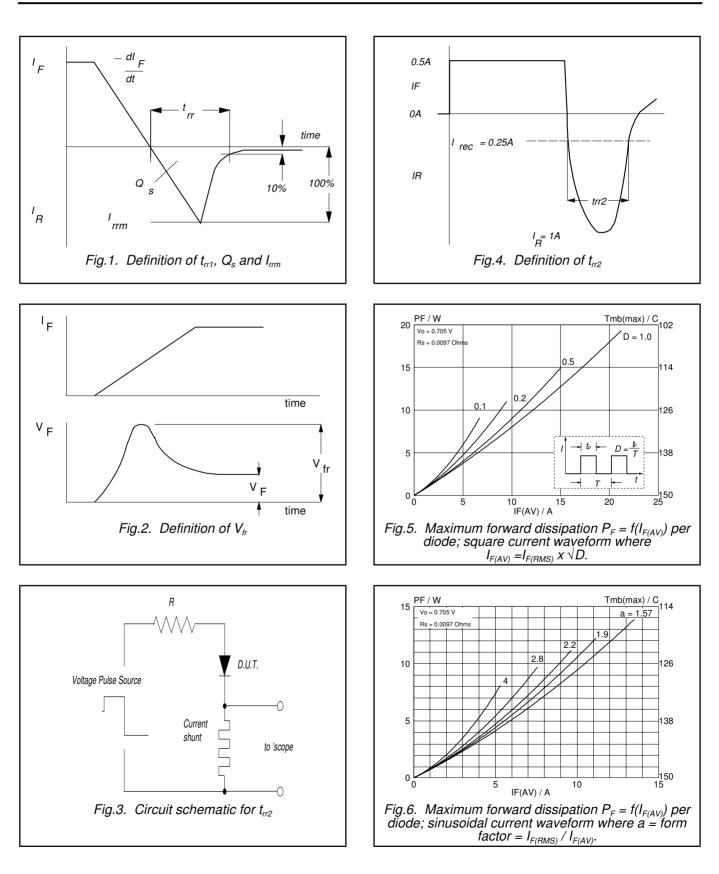
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb} R _{th j-a}	Thermal resistance junction to mounting base Thermal resistance junction to ambient	per diode both diodes SOT78 package, in free air SOT404 and SOT428 packages, pcb mounted, minimum footprint, FR4 board		- 60 50	2.4 1.4 - -	K/W K/W K/W K/W

ELECTRICAL CHARACTERISTICS

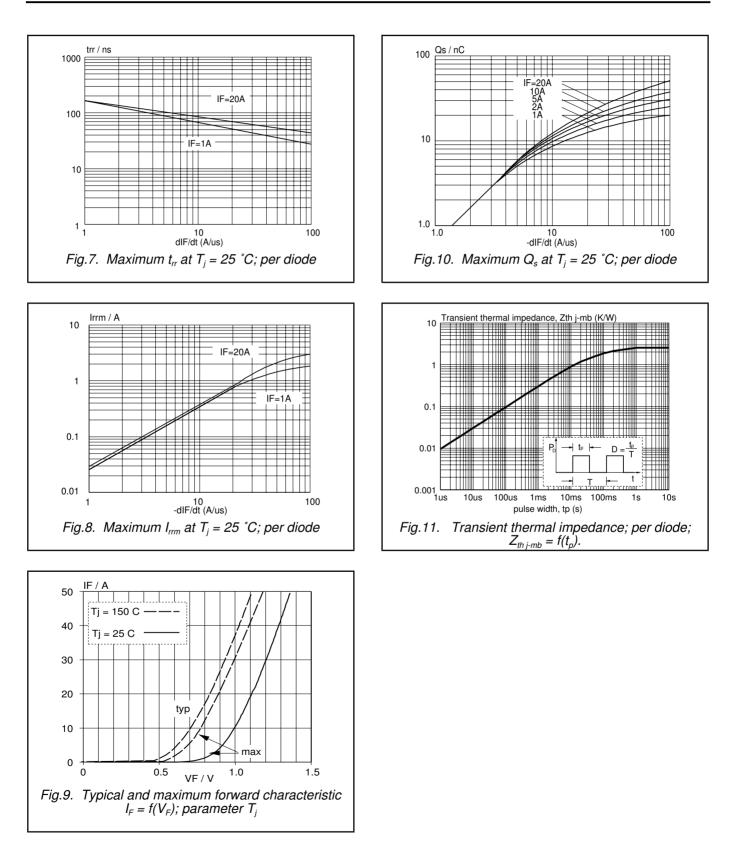
characteristics are per diode at $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _F	Forward voltage	I _F = 15 A; T _i = 150°C	-	0.78	0.85	V
	-	$I_{\rm F} = 15 {\rm A}^{-1}$	-	0.95	1.05	V
		$I_{\rm F} = 30 {\rm A}$	-	1.00	1.20	V
I _R	Reverse current	$\dot{V}_{R} = V_{RWM}; T_{j} = 100 \ ^{\circ}C$	-	0.5	1	mA
		$V_{\rm B} = V_{\rm BWM}$	-	10	100	μA
Q_s	Reverse recovery charge	$ I_{\rm F} = 2 \text{ A}; V_{\rm B} \ge 30 \text{ V}; -dI_{\rm F}/dt = 20 \text{ A}/\mu\text{s}$	-	6	15	'nC
t _{rr1}	Reverse recovery time	$I_{\rm F} = 1 \text{ A}; V_{\rm R} \ge 30 \text{ V};$	-	20	28	ns
		-dI _F /dt = 100 A/μs				
t _{rr2}	Reverse recovery time	$I_{\rm F} = 0.5 \text{ A to } I_{\rm R} = 1 \text{ A}$; $I_{\rm rec} = 0.25 \text{ A}$	-	13	22	ns
V _{fr}	Forward recovery voltage	$I_{F} = 1 \text{ A}; dI_{F}/dt = 10 \text{ A}/\mu s$	-	1	-	V

BYV42E, BYV42EB series

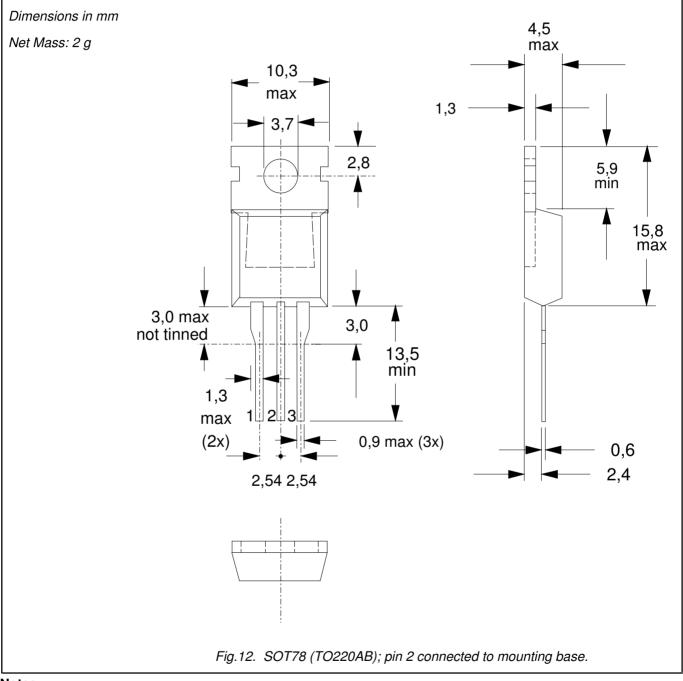


BYV42E, BYV42EB series



BYV42E, BYV42EB series

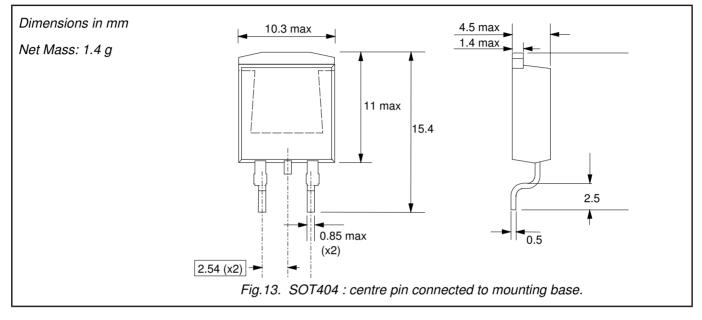
MECHANICAL DATA



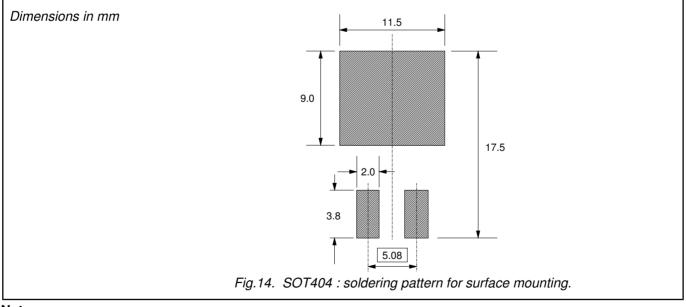
Notes 1. Refer to mounting instructions for SOT78 (TO220) envelopes. 2. Epoxy meets UL94 V0 at 1/8".

BYV42E, BYV42EB series

MECHANICAL DATA



MOUNTING INSTRUCTIONS



Notes

1. Epoxy meets UL94 V0 at 1/8".

Legal information

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Contact information

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